

**COPOLYMERIZED POLYIMIDE, COPOLYMERIZED POLYIMIDE RESIN  
MOLDING AND THEIR PRODUCTION**

Patent Number: JP9235373  
Publication date: 1997-09-09  
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Requested Patent: ☐ JP9235373  
Application Number: JP19960354105 19961217  
Priority Number(s):  
IPC Classification: C08G73/10; C08J5/00  
EC Classification:  
Equivalents:

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**Abstract**

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**PROBLEM TO BE SOLVED:** To obtain a polyimide copolymer which can produce a molded product of high elastic modulus, low thermal expansion and low water absorption and is useful as a TAB base film by molecularly binding a specific block polyimide component to a randomly copolymerized polyimide component.

**SOLUTION:** (A) A polyimide block component from an aromatic diamine of a rigid structure of formula I (X is H, a halogen, carboxyl, a lower alkyl, a lower alkoxy) such as p-phenylenediamine (A1 ) and an aromatic tetracarboxylic acid, for example, pyromellitic acid, 3,3',4,4'- biphenyltetracarboxylic acid or 3, 3',4,4'- benzophenone-tetracarboxylic acid (A2 ) and (B) a polyimide random copolymer component from an aromatic diamine of a flexible structure of formula II (Y is X; A is O, S, CO, SO, SO<sub>2</sub> , CH<sub>2</sub> ), for example, 4,4'-diaminodiphenyl ether (B1 ) and 2 or more kinds of A2 are molecularly bonded to each other.

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